Icemos Technology Ltd Product Specification 1000.717201 Issue Date 22 March 2022 16:09:

Dart Manakan	Contained
Part Number	Customer

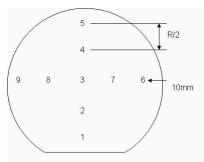
Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.20 mm	
	2.0	Primary Flat Orientation	<110> +/- 0.5 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none / Semi Standard	
	5.0	Secondary Flat Length	none	Wafer Vendor
	6.0	Overall Thickness	412.00 +/- 12.00 μm	ADE 100%
	7.0	Total Thickness Variation (TTV)	<3.00μm	Guaranteed by Process
	8.0	Bow	<60.00μm	ADE to ASTM F534, 20%
	9.0	Warp	<60.00μm	ADE to ASTM F657, 20%
	10.0	Edge Chips	0	Bright Light, 100% (note 2)
	11.0	Edge Exclusion	5mm	
HandleSilicon	12.0	Handle Growth Method	CZ	Wafer Vendor
	13.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	14.0	Handle Thickness	380.00 +/- 10.00 μm	ADE, 100%
	15.0	Handle Doping Type	Р	Wafer Vendor
	16.0	Handle Dopant	Boron	Wafer Vendor
	17.0	Handle Resistivity	0.01 ~ 0.02 Ohmcm	Wafer Vendor
	18.0	Handle Oxygen Concentration	< 16ppma (ASTM-83; new)	Wafer Vendor
	19.0	Backside Finish	Polished with oxide and lasermark	Wafer Vendor
BuriedOxide	20.0	Oxide Type	Thermal	
	21.0	Oxide Thickness	20,000.00 +/- 1,000.00 A	Nanospec centre point, 4%
	22.0	Oxide formed on	Handle and/or Device Wafer	
DeviceSilicon	23.0	Device Growth Method	CZ	Wafer Vendor
	24.0	Device Orientation	{100} +/- 1 degree	Wafer Vendor
	25.0	Nominal Thickness	30.00 +/- 1.00 μm	FTIR, 100% 9-Pt (note3)
	26.0	Distance to device silicon edge from wafer edge	< 2 mm	Guaranteed by Process
	27.0	Device Doping Type	P	Wafer Vendor
	28.0	Device Dopant	Boron	Wafer Vendor
	29.0	Device Resistivity	0.01~ 0.02 Ohmcm	Wafer Vendor
	30.0	Oxygen Concentration	< 16ppma (ASTM-83; new)	Wafer Vendor
	31.0	Voids	0	Bright Light, 100% (note 2)
	32.0	Scratches	0	Bright Light, 100% (note 2)
	33.0	Haze	none	Bright Light, 100% (note 2)

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Part Number		Customer	
Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging:	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspec	etion performed using microscope scan as below. 5x objective.	
2. All bright lig		pections performed exclude all wafer area outside the edge exclusion	on defined in Overall

2. All bright light inspections performed exclude all water area outside the edge exclusion defined in Overal Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information